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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	1803
Number of Logic Elements/Cells	28848
Total RAM Bits	608256
Number of I/O	532
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	780-BGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep4ce30f29i8l">https://www.e-xfl.com/product-detail/intel/ep4ce30f29i8l</a>

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## Cyclone IV Device Family Architecture

This section describes Cyclone IV device architecture and contains the following topics:

- “FPGA Core Fabric”
- “I/O Features”
- “Clock Management”
- “External Memory Interfaces”
- “Configuration”
- “High-Speed Transceivers (Cyclone IV GX Devices Only)”
- “Hard IP for PCI Express (Cyclone IV GX Devices Only)”

### FPGA Core Fabric

Cyclone IV devices leverage the same core fabric as the very successful Cyclone series devices. The fabric consists of LEs, made of 4-input look up tables (LUTs), memory blocks, and multipliers.

Each Cyclone IV device M9K memory block provides 9 Kbits of embedded SRAM memory. You can configure the M9K blocks as single port, simple dual port, or true dual port RAM, as well as FIFO buffers or ROM. They can also be configured to implement any of the data widths in Table 1–7.

**Table 1–7. M9K Block Data Widths for Cyclone IV Device Family**

Mode	Data Width Configurations
Single port or simple dual port	×1, ×2, ×4, ×8/9, ×16/18, and ×32/36
True dual port	×1, ×2, ×4, ×8/9, and ×16/18

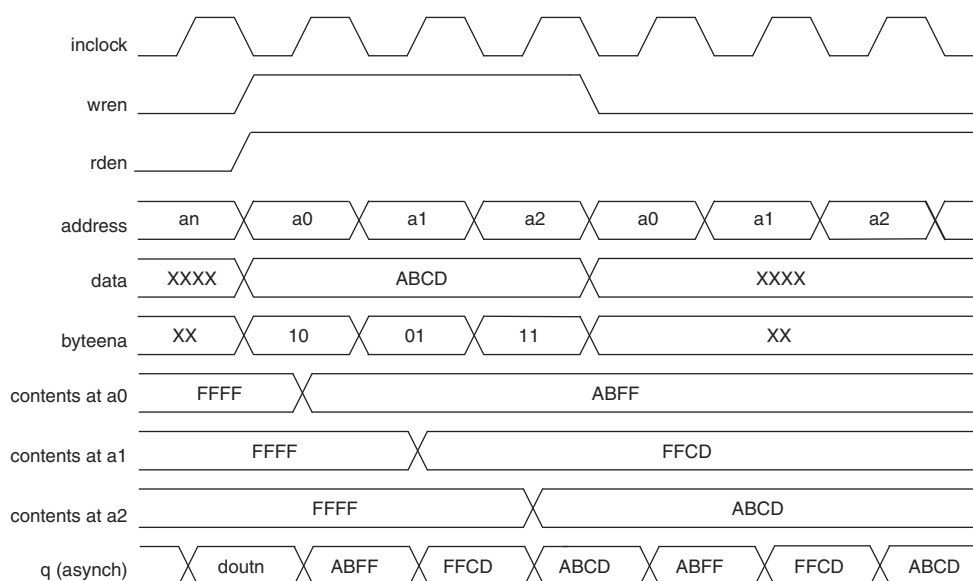
The multiplier architecture in Cyclone IV devices is the same as in the existing Cyclone series devices. The embedded multiplier blocks can implement an  $18 \times 18$  or two  $9 \times 9$  multipliers in a single block. Altera offers a complete suite of DSP IP including finite impulse response (FIR), fast Fourier transform (FFT), and numerically controlled oscillator (NCO) functions for use with the multiplier blocks. The Quartus® II design software’s DSP Builder tool integrates MathWorks Simulink and MATLAB design environments for a streamlined DSP design flow.



For more information, refer to the *Logic Elements and Logic Array Blocks in Cyclone IV Devices*, *Memory Blocks in Cyclone IV Devices*, and *Embedded Multipliers in Cyclone IV Devices* chapters.

Figure 3-1 shows how the wren and byteena signals control the RAM operations.

**Figure 3-1. Cyclone IV Devices byteena Functional Waveform <sup>(1)</sup>**



**Note to Figure 3-1:**

(1) For this functional waveform, **New Data** mode is selected.

When a byteena bit is deasserted during a write cycle, the old data in the memory appears in the corresponding data-byte output. When a byteena bit is asserted during a write cycle, the corresponding data-byte output depends on the setting chosen in the Quartus® II software. The setting can either be the newly written data or the old data at that location.



Byte enables are only supported for True Dual-Port memory configurations when both the PortA and PortB data widths of the individual M9K memory blocks are multiples of 8 or 9 bits.

## Packed Mode Support

Cyclone IV devices M9K memory blocks support packed mode. You can implement two single-port memory blocks in a single block under the following conditions:

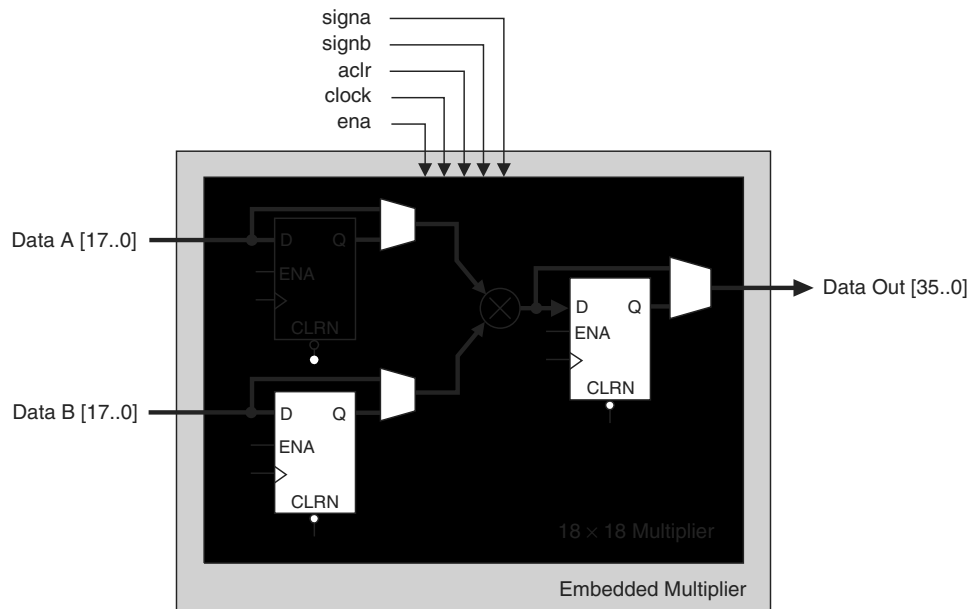
- Each of the two independent block sizes is less than or equal to half of the M9K block size. The maximum data width for each independent block is 18 bits wide.
- Each of the single-port memory blocks is configured in single-clock mode. For more information about packed mode support, refer to “Single-Port Mode” on page 3-8 and “Single-Clock Mode” on page 3-15.

## 18-Bit Multipliers

You can configure each embedded multiplier to support a single  $18 \times 18$  multiplier for input widths of 10 to 18 bits.

Figure 4-3 shows the embedded multiplier configured to support an 18-bit multiplier.

**Figure 4-3. 18-Bit Multiplier Mode**



All 18-bit multiplier inputs and results are independently sent through registers. The multiplier inputs can accept signed integers, unsigned integers, or a combination of both. Also, you can dynamically change the **signa** and **signb** signals and send these signals through dedicated input registers.



For more information about the number of GCLK networks in each device density, refer to the *Cyclone IV FPGA Device Family Overview* chapter.

## GCLK Network

GCLKs drive throughout the entire device, feeding all device quadrants. All resources in the device (I/O elements, logic array blocks (LABs), dedicated multiplier blocks, and M9K memory blocks) can use GCLKs as clock sources. Use these clock network resources for control signals, such as clock enables and clears fed by an external pin. Internal logic can also drive GCLKs for internally generated GCLKs and asynchronous clears, clock enables, or other control signals with high fan-out.

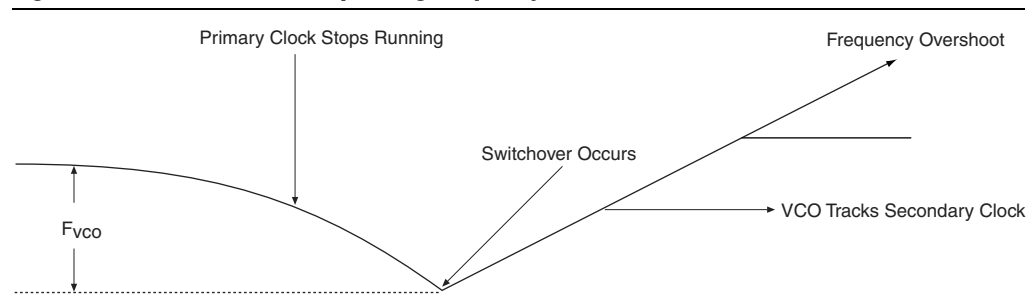
Table 5-1, Table 5-2 on page 5-4, and Table 5-3 on page 5-7 list the connectivity of the clock sources to the GCLK networks.

**Table 5-1. GCLK Network Connections for EP4CGX15, EP4CGX22, and EP4CGX30 <sup>(1)</sup>, <sup>(2)</sup> (Part 1 of 2)**

GCLK Network Clock Sources	GCLK Networks																			
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19
CLK4/DIFFCLK_2n	—	—	—	—	—	✓	—	✓	—	✓	—	—	—	—	—	—	—	—	—	—
CLK5/DIFFCLK_2p	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—
CLK6/DIFFCLK_3n	—	—	—	—	—	—	✓	—	✓	✓	—	—	—	—	—	—	—	—	—	—
CLK7/DIFFCLK_3p	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—	—	—	—	—	—
CLK8/DIFFCLK_5n	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—	✓	—	—	—	—	—
CLK9/DIFFCLK_5p	—	—	—	—	—	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	—
CLK10/DIFFCLK_4n/RE FCLK1n	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	✓	—	—	—	—	—
CLK11/DIFFCLK_4p/RE FCLK1p	—	—	—	—	—	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—
CLK12/DIFFCLK_7p/RE FCLK0p	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—	✓
CLK13/DIFFCLK_7n/RE FCLK0n	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	✓	—	—
CLK14/DIFFCLK_6p	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	✓
CLK15/DIFFCLK_6n	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	—	✓	—
PLL_1_C0	✓	—	—	✓	—	—	—	—	—	—	—	—	—	—	—	✓	—	—	✓	—
PLL_1_C1	—	✓	—	—	✓	—	—	—	—	—	—	—	—	—	—	—	✓	—	—	✓
PLL_1_C2	✓	—	✓	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—	—
PLL_1_C3	—	✓	—	✓	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—
PLL_1_C4	—	—	✓	—	✓	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓
PLL_2_C0	✓	—	—	✓	—	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—
PLL_2_C1	—	✓	—	—	✓	—	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—
PLL_2_C2	✓	—	✓	—	—	—	—	—	—	—	✓	—	✓	—	—	—	—	—	—	—
PLL_2_C3	—	✓	—	✓	—	—	—	—	—	—	—	✓	—	✓	—	—	—	—	—	—
PLL_2_C4	—	—	✓	—	✓	—	—	—	—	—	—	—	✓	—	✓	—	—	—	—	—
PLL_3_C0	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—	✓	—	—	✓	—

- When using manual clock switchover, the difference between `inclk0` and `inclk1` can be more than 20%. However, differences between the two clock sources (frequency, phase, or both) can cause the PLL to lose lock. Resetting the PLL ensures that the correct phase relationships are maintained between the input and output clocks.
- Both `inclk0` and `inclk1` must be running when the `clkswitch` signal goes high to start the manual clock switchover event. Failing to meet this requirement causes the clock switchover to malfunction.
- Applications that require a clock switchover feature and a small frequency drift must use a low-bandwidth PLL. When referencing input clock changes, the low-bandwidth PLL reacts slower than a high-bandwidth PLL. When the switchover happens, the low-bandwidth PLL propagates the stopping of the clock to the output slower than the high-bandwidth PLL. The low-bandwidth PLL filters out jitter on the reference clock. However, the low-bandwidth PLL also increases lock time.
- After a switchover occurs, there may be a finite resynchronization period for the PLL to lock onto a new clock. The exact amount of time it takes for the PLL to re-lock is dependent on the PLL configuration.
- If the phase relationship between the input clock to the PLL and output clock from the PLL is important in your design, assert `areset` for 10 ns after performing a clock switchover. Wait for the locked signal (or gated lock) to go high before re-enabling the output clocks from the PLL.
- Figure 5–20 shows how the VCO frequency gradually decreases when the primary clock is lost and then increases as the VCO locks on to the secondary clock. After the VCO locks on to the secondary clock, some overshoot can occur (an over-frequency condition) in the VCO frequency.

**Figure 5–20. VCO Switchover Operating Frequency**



- Disable the system during switchover if the system is not tolerant to frequency variations during the PLL resynchronization period. You can use the `clkbad0` and `clkbad1` status signals to turn off the PFD (`pfdena = 0`) so the VCO maintains its last frequency. You can also use the switchover state machine to switch over to the secondary clock. Upon enabling the PFD, output clock enable signals (`clkena`) can disable clock outputs during the switchover and resynchronization period. After the lock indication is stable, the system can re-enable the output clock or clocks.

The CLKIN/REFCLK pins are powered by dedicated  $V_{CC\_CLKIN3A}$ ,  $V_{CC\_CLKIN3B}$ ,  $V_{CC\_CLKIN8A}$ , and  $V_{CC\_CLKIN8B}$  power supplies separately in their respective I/O banks to avoid the different power level requirements in the same bank for GPIO.

**Table 6-10. Cyclone IV GX HSSI REFCLK I/O Standard Support Using GPIO CLKIN Pins <sup>(1)</sup>, <sup>(2)</sup>**

I/O Standard	HSSI Protocol	Coupling	Termination	VCC_CLKIN Level		I/O Pin Type		
				Input	Output	Column I/O	Row I/O	Supported I/O Banks
LVDS	All	Differential AC (Need off chip resistor to restore $V_{CM}$ )	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B
LVPECL	All		Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B
1.2V, 1.5V, 3.3V PCML	All		Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B
	All		Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B
	All		Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B
HCSL	PCIe	Differential DC	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B

**Notes to Table 6-10:**

- (1) The EP4CGX15, EP4CGX22, and EP4CGX30 devices have two pairs of dedicated clock input pins in banks 3A and 8A for HSSI input reference clock. I/O banks 3B and 8B are not available in EP4CGX15, EP4CGX22, and EP4CGX30 devices.
- (2) The EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices have four pairs of dedicated clock input pins in banks 3A, 3B, 8A, and 8B for HSSI input or single-ended clock input.



For more information about the AC-coupled termination scheme for the HSSI reference clock, refer to the *Cyclone IV Transceivers Architecture* chapter.

## LVDS I/O Standard Support in Cyclone IV Devices

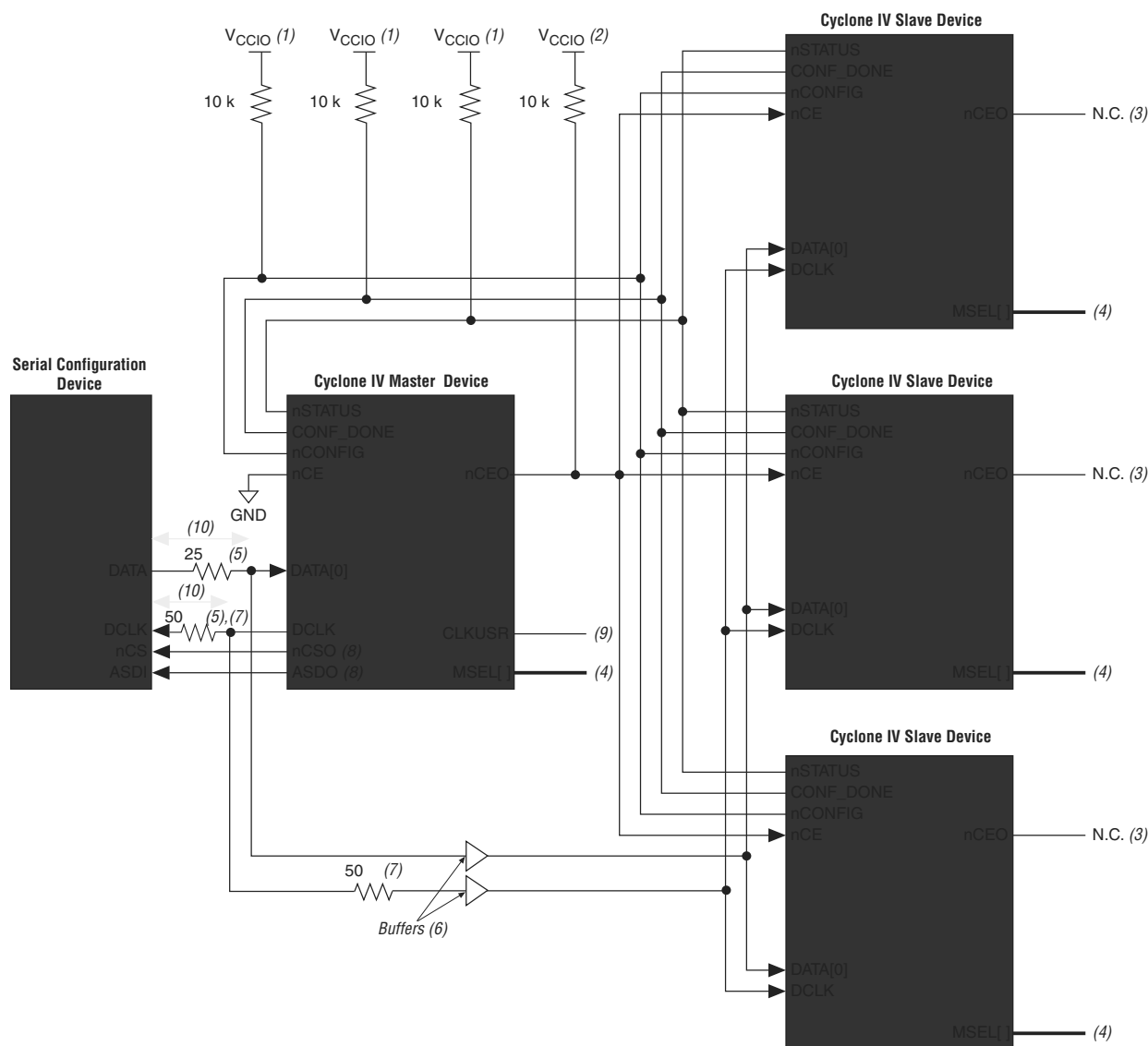
The LVDS I/O standard is a high-speed, low-voltage swing, low power, and GPIO interface standard. Cyclone IV devices meet the ANSI/TIA/EIA-644 standard with the following exceptions:

- The maximum differential output voltage ( $V_{OD}$ ) is increased to 600 mV. The maximum  $V_{OD}$  for ANSI specification is 450 mV.
- The input voltage range is reduced to the range of 1.0 V to 1.6 V, 0.5 V to 1.85 V, or 0 V to 1.8 V based on different frequency ranges. The ANSI/TIA/EIA-644 specification supports an input voltage range of 0 V to 2.4 V.



For LVDS I/O standard electrical specifications in Cyclone IV devices, refer to the *Cyclone IV Device Datasheet* chapter.

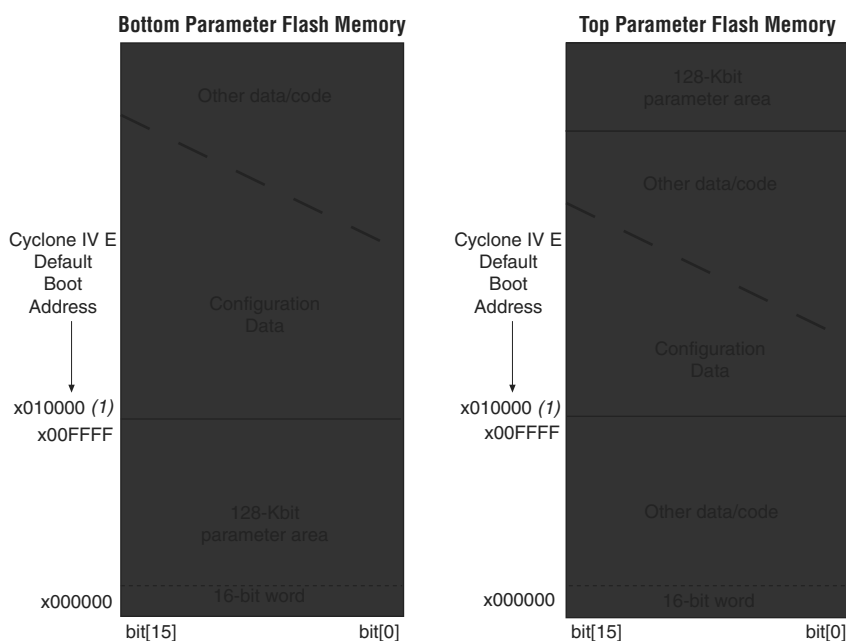


**Figure 8-4. Multi-Device AS Configuration in Which Devices Receive the Same Data with Multiple .sof****Notes to Figure 8-4:**

- (1) Connect the pull-up resistors to the  $V_{CCIO}$  supply of the bank in which the pin resides.
- (2) Connect the pull-up resistor to the  $V_{CCIO}$  supply voltage of the I/O bank in which the  $nCE$  pin resides.
- (3) The  $nCEO$  pin is left unconnected or used as a user I/O pin when it does not feed the  $nCE$  pin of another device.
- (4) The  $MSEL$  pin settings vary for different configuration voltage standards and POR time. You must set the master device in AS mode and the slave devices in PS mode. To connect the  $MSEL$  pins for the master device in AS mode and the slave devices in PS mode, refer to Table 8-3 on page 8-8, Table 8-4 on page 8-8, and Table 8-5 on page 8-9. Connect the  $MSEL$  pins directly to  $V_{CCA}$  or GND.
- (5) Connect the series resistor at the near end of the serial configuration device.
- (6) Connect the repeater buffers between the master and slave devices for  $DATA[0]$  and  $DCLK$ . All I/O inputs must maintain a maximum AC voltage of 4.1 V. The output resistance of the repeater buffers must fit the maximum overshoot equation outlined in "Configuration and JTAG Pin I/O Requirements" on page 8-5.
- (7) The 50-Ω series resistors are optional if the 3.3-V configuration voltage standard is applied. For optimal signal integrity, connect these 50-Ω series resistors if the 2.5- or 3.0-V configuration voltage standard is applied.
- (8) These pins are dual-purpose I/O pins. The  $nCSO$  pin functions as  $FLASH\_nCE$  pin in AP mode. The  $ASDO$  pin functions as  $DATA[1]$  pin in AP and FPP modes.
- (9) Only Cyclone IV GX devices have an option to select  $CLKUSR$  (40 MHz maximum) as the external clock source for  $DCLK$ .
- (10) For multi-devices AS configuration using Cyclone IV E with 1.0 V core voltage, the maximum board trace-length from the serial configuration device to the junction-split on both  $DCLK$  and  $Data0$  line is 3.5 inches.

The default configuration boot address allows the system to use special parameter blocks in the flash memory map. Parameter blocks are at the top or bottom of the memory map. Figure 8–12 shows the configuration boot address in the AP configuration scheme. You can change the default configuration default boot address 0x010000 to any desired address using the APFC\_BOOT\_ADDR JTAG instruction. For more information about the APFC\_BOOT\_ADDR JTAG instruction, refer to “JTAG Instructions” on page 8–57.

**Figure 8–12. Configuration Boot Address in AP Flash Memory Map**



**Note to Figure 8–12:**

(1) The default configuration boot address is x010000 when represented in 16-bit word addressing.

## PS Configuration

You can perform PS configuration on Cyclone IV devices with an external intelligent host, such as a MAX<sup>®</sup> II device, microprocessor with flash memory, or a download cable. In the PS scheme, an external host controls the configuration. Configuration data is clocked into the target Cyclone IV device through DATA[0] at each rising edge of DCLK.

If your system already contains a common flash interface (CFI) flash memory, you can use it for Cyclone IV device configuration storage as well. The MAX II PFL feature provides an efficient method to program CFI flash memory devices through the JTAG interface and the logic to control the configuration from the flash memory device to the Cyclone IV device.



For more information about the PFL, refer to *AN 386: Using the Parallel Flash Loader with the Quartus II Software*.



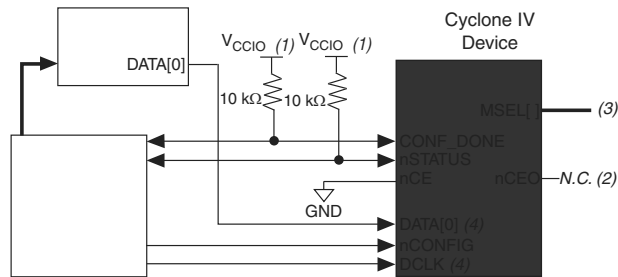
Cyclone IV devices do not support enhanced configuration devices for PS configuration.

## PS Configuration Using an External Host

In the PS configuration scheme, you can use an intelligent host such as a MAX II device or microprocessor that controls the transfer of configuration data from a storage device, such as flash memory, to the target Cyclone IV device. You can store the configuration data in **.rbf**, **.hex**, or **.ttf** format.

Figure 8-13 shows the configuration interface connections between a Cyclone IV device and an external host device for single-device configuration.

**Figure 8-13. Single-Device PS Configuration Using an External Host**



### Notes to Figure 8-13:

- (1) Connect the pull-up resistor to a supply that provides an acceptable input signal for the device.  $V_{CC}$  must be high enough to meet the  $V_{IH}$  specification of the I/O on the device and the external host.
- (2) The  $n_{CEO}$  pin is left unconnected or used as a user I/O pin when it does not feed the  $n_{CE}$  pin of another device.
- (3) The  $MSEL$  pin settings vary for different configuration voltage standards and POR time. To connect the  $MSEL$  pins, refer to Table 8-3 on page 8-8, Table 8-4 on page 8-8, and Table 8-5 on page 8-9. Connect the  $MSEL$  pins directly to  $V_{CCA}$  or GND.
- (4) All I/O inputs must maintain a maximum AC voltage of 4.1 V.  $DATA[0]$  and  $DCLK$  must fit the maximum overshoot outlined in Equation 8-1 on page 8-5.

To begin the configuration, the external host device must generate a low-to-high transition on the  $n_{CONFIG}$  pin. When  $n_{STATUS}$  is pulled high, the external host device must place the configuration data one bit at a time on  $DATA[0]$ . If you use configuration data in **.rbf**, **.ttf**, or **.hex**, you must first send the LSB of each data byte. For example, if the **.rbf** contains the byte sequence 02 1B EE 01 FA, the serial bitstream you must send to the device is:

0100-0000 1101-1000 0111-0111 1000-0000 0101-1111

Cyclone IV devices receive configuration data on  $DATA[0]$  and the clock is received on  $DCLK$ . Data is latched into the device on the rising edge of  $DCLK$ . Data is continuously clocked into the target device until  $CONF\_DONE$  goes high and the device enters initialization state.



Two  $DCLK$  falling edges are required after  $CONF\_DONE$  goes high to begin the initialization of the device.

$INIT\_DONE$  is released and pulled high when initialization is complete. The external host device must be able to detect this low-to-high transition which signals the device has entered user mode. When initialization is complete, the device enters user mode. In user mode, the user I/O pins no longer have weak pull-up resistors and function as assigned in your design.



**Table 11-1. Power Supply Descriptions for the Cyclone IV GX Devices (Part 2 of 2)**

Power Supply Pin	Nominal Voltage Level (V)	Description
VCCCL_GXB	1.2	Transceiver PMA and auxiliary power supply

**Notes to Table 11-1:**

- (1) You must power up VCCA even if the phase-locked loop (PLL) is not used.
- (2) I/O banks 3, 8, and 9 contain configuration pins. You can only power up the V<sub>CCIO</sub> level of I/O banks 3 and 9 to 1.5 V, 1.8 V, 2.5 V, 3.0 V, or 3.3 V. For Fast Passive Parallel (FPP) configuration mode, you must power up the V<sub>CCIO</sub> level of I/O bank 8 to 1.5 V, 1.8 V, 2.5 V, 3.0 V, or 3.3 V.
- (3) All device packages of EP4CGX15, EP4CGX22, and device package F169 and F324 of EP4CGX30 devices have two VCC\_CLKIN dedicated clock input I/O located at Banks 3A and 8A. Device package F484 of EP4CGX30, all device packages of EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices have four VCC\_CLKIN dedicated clock input I/O bank located at banks 3A, 3B, 8A, and 8B.
- (4) You must set VCC\_CLKIN to 2.5V if the CLKIN is used as a high-speed serial interface (HSSI) transceiver refclk. When not used as a transceiver refclk, VCC\_CLKIN supports 1.2 V/ 1.5 V/ 1.8 V/ 2.5 V/ 3.0 V/ 3.3V voltages.

**Table 11-2. Power Supply Descriptions for the Cyclone IV E Devices**

Power Supply Pin	Nominal Voltage Level (V)	Description
VCCINT	1.0, 1.2	Core voltage power supply
VCCA <sup>(1)</sup>	2.5	PLL analog power supply
VCCD_PLL	1.0, 1.2	PLL digital power supply
VCCIO <sup>(2)</sup>	1.2, 1.5, 1.8, 2.5, 3.0, 3.3	I/O banks power supply

**Notes to Table 11-2:**

- (1) You must power up VCCA even if the PLL is not used.
- (2) I/O banks 1, 6, 7, and 8 contain configuration pins.

## Hot-Socketing Specifications

Cyclone IV devices are hot-socketing compliant without the need for any external components or special design requirements. Hot-socketing support in Cyclone IV devices has the following advantages:

- You can drive the device before power up without damaging the device.
- I/O pins remain tri-stated during power up. The device does not drive out before or during power-up. Therefore, it does not affect other buses in operation.

### Devices Driven Before Power-Up

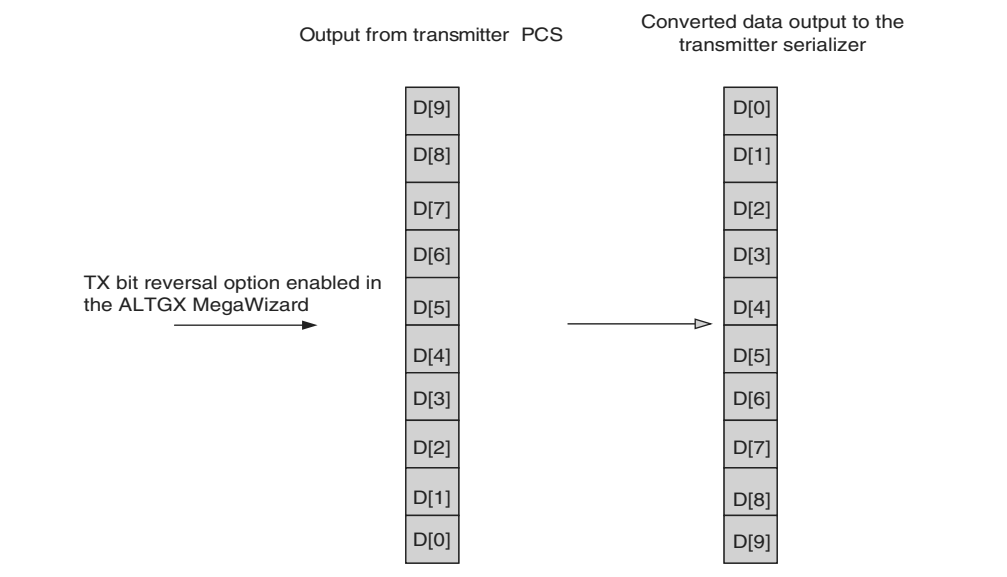
You can drive signals into regular Cyclone IV E I/O pins and transceiver Cyclone IV GX I/O pins before or during power up or power down without damaging the device. Cyclone IV devices support any power-up or power-down sequence to simplify system-level designs.

### I/O Pins Remain Tri-stated During Power-Up

The output buffers of Cyclone IV devices are turned off during system power up or power down. Cyclone IV devices do not drive out until the device is configured and working in recommended operating conditions. The I/O pins are tri-stated until the device enters user mode.

- Bit reversal—reverses the transmit bit order from LSB-to-MSB (default) to MSB-to-LSB at the input to the serializer. For example, input data to serializer  $D[7..0]$  is rewired to  $D[0..7]$  for 8-bit data width, and  $D[9..0]$  is rewired to  $D[0..9]$  for 10-bit data width. Figure 1–10 shows the transmitter bit reversal feature.

**Figure 1–10. Transmitter Bit Reversal Operation in Basic Single-Width Mode**



- Input bit-flip—reverses the bit order at a byte level at the input of the transmitter phase compensation FIFO. For example, if the 16-bit parallel transmitter data at the `tx_datain` port is '10111100 10101101' (16'hBCAD), selecting this option reverses the input data to the transmitter phase compensation FIFO to '00111101 10110101' (16'h3DB5).
- Bit-slip control—delays the data transmission by a number of specified bits to the serializer with the `tx_bitslipboundaryselect` port. For usage details, refer to the "Transmit Bit-Slip Control" on page 1–76.

## Serializer

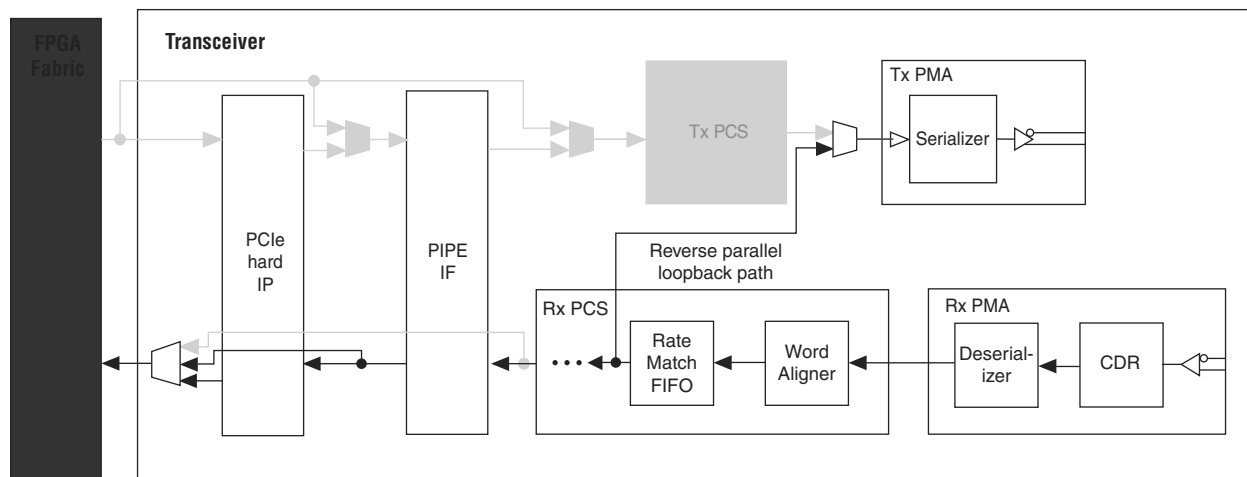
The serializer converts the low-speed parallel 8-bit or 10-bit data from the transmitter PCS to high-speed serial data for the transmitter output buffer. The serializer operates with a high-speed clock at half of the serial data rate. The serializer transmission sequence is LSB to MSB.

## Reverse Parallel Loopback

The reverse parallel loopback option is only available for PIPE mode. In this mode, the received serial data passes through the receiver CDR, deserializer, word aligner, and rate match FIFO before looping back to the transmitter serializer and transmitted out through the TX buffer, as shown in Figure 1-70. The received data is also available to the FPGA fabric. This loopback mode is compliant with version 2.00 of the *PHY Interface for the PCI Express Architecture* specification.

To enable the reverse parallel loopback mode, assert the tx\_detectrxloopback port in P0 power state.

**Figure 1-70. PIPE Reverse Parallel Loopback Path <sup>(1)</sup>**



**Note to Figure 1-70:**

(1) Grayed-Out Blocks are Not Active in this mode.

## Serial Loopback

The serial loopback option is available for all functional modes except PIPE mode. In this mode, the data from the FPGA fabric passes through the transmitter channel and looped back to the receiver channel, bypassing the receiver buffer, as shown in Figure 1-71. The received data is available to the FPGA logic for verification. The receiver input buffer is not active in this mode. With this option, you can check the operation of all enabled PCS and PMA functional blocks in the transmitter and receiver channels.

The transmitter channel sends the data to both the serial output port and the receiver channel. The differential output voltage on the serial ports is based on the selected  $V_{OD}$  settings. The data is looped back to the receiver CDR and is retimed through different clock domains. You must provide an alignment pattern for the word aligner to enable the receiver channel to retrieve the byte boundary.

**Table 2-3. Blocks Affected by Reset and Power-Down Signals (Part 2 of 2)**

Transceiver Block	rx_digitalreset	rx_analogreset	tx_digitalreset	pll_aret	gxb_powerdown
Serializer	—	—	✓	—	✓
Transmitter Buffer	—	—	—	—	✓
Transmitter XAUI State Machine	—	—	✓	—	✓
Receiver Buffer	—	—	—	—	✓
Receiver CDR	—	✓	—	—	✓
Receiver Deserializer	—	—	—	—	✓
Receiver Word Aligner	✓	—	—	—	✓
Receiver Deskew FIFO	✓	—	—	—	✓
Receiver Clock Rate Compensation FIFO	✓	—	—	—	✓
Receiver 8B/10B Decoder	✓	—	—	—	✓
Receiver Byte Deserializer	✓	—	—	—	✓
Receiver Byte Ordering	✓	—	—	—	✓
Receiver Phase Compensation FIFO	✓	—	—	—	✓
Receiver XAUI State Machine	✓	—	—	—	✓
BIST Verifiers	✓	—	—	—	✓

## Transceiver Reset Sequences

You can configure transceiver channels in Cyclone IV GX devices in various configurations. In all functional modes except XAUI functional mode, transceiver channels can be either bonded or non-bonded. In XAUI functional mode, transceiver channels must be bonded. In PCI Express® (PCIe®) functional mode, transceiver channels can be either bonded or non-bonded and need to follow a specific reset sequence.

The two categories of reset sequences for Cyclone IV GX devices described in this chapter are:

- “All Supported Functional Modes Except the PCIe Functional Mode” on page 2-6—describes the reset sequences in bonded and non-bonded configurations.
- “PCIe Functional Mode” on page 2-17—describes the reset sequence for the initialization/compliance phase and the normal operation phase in PCIe functional modes.



# 3. Cyclone IV Dynamic Reconfiguration

CYIV-52003-2.1

Cyclone® IV GX transceivers allow you to dynamically reconfigure different portions of the transceivers without powering down any part of the device. This chapter describes and provides examples about the different modes available for dynamic reconfiguration.

You can use the ALTGX\_RECONFIG and ALTPLL\_RECONFIG controller instance to reconfigure the physical medium attachment (PMA) controls, physical coding sublayer (PCS), multipurpose phase locked loops (PLLs), and general purpose PLLs.

This chapter contains the following sections:

- “Glossary of Terms” on page 3–1
- “Dynamic Reconfiguration Controller Architecture” on page 3–2
- “Dynamic Reconfiguration Modes” on page 3–12
- “Error Indication During Dynamic Reconfiguration” on page 3–36
- “Functional Simulation of the Dynamic Reconfiguration Process” on page 3–37

## Glossary of Terms

Table 3–1 lists the terms used in this chapter:

**Table 3–1. Glossary of Terms Used in this Chapter (Part 1 of 2)**

Term	Description
ALTGX_RECONFIG Instance	Dynamic reconfiguration controller instance generated by the ALTGX_RECONFIG MegaWizard™ Plug-In Manager.
ALTGX Instance	Transceiver instance generated by the ALTGX MegaWizard Plug-In Manager.
ALTPLL_RECONFIG Instance	Dynamic PLL reconfiguration controller instance generated by the ALTPLL_RECONFIG Megawizard Plug-In Manager
Logical Channel Addressing	Used whenever the concept of logical channel addressing is explained. This term does not refer to the <code>logical_channel_address</code> port available in the ALTGX_RECONFIG MegaWizard Plug-In Manager.

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There are three methods that you can use to dynamically reconfigure the PMA controls of a transceiver channel:

- “Method 1: Using `logical_channel_address` to Reconfigure Specific Transceiver Channels” on page 3-14
- “Method 2: Writing the Same Control Signals to Control All the Transceiver Channels” on page 3-16
- “Method 3: Writing Different Control Signals for all the Transceiver Channels at the Same Time” on page 3-19

### Method 1: Using `logical_channel_address` to Reconfigure Specific Transceiver Channels

Enable the `logical_channel_address` port by selecting the **Use 'logical\_channel\_address' port** option on the **Analog controls** tab. This method is applicable only for a design where the dynamic reconfiguration controller controls more than one channel.

You can additionally reconfigure either the receiver portion, transmitter portion, or both the receiver and transmitter portions of the transceiver channel by setting the corresponding value on the `rx_tx_duplex_sel` input port. For more information, refer to Table 3-2 on page 3-4.

#### Connecting the PMA Control Ports

The selected PMA control ports remain fixed in width, regardless of the number of channels controlled by the ALTGX\_RECONFIG instance:

- `tx_vodctrl` and `tx_vodctrl_out` are fixed to 3 bits
- `tx_preemp` and `tx_preemp_out` are fixed to 5 bits
- `rx_eqdcgain` and `rx_eqdcgain_out` are fixed to 2 bits
- `rx_eqctrl` and `rx_eqctrl_out` are fixed to 4 bits

#### Write Transaction

To complete a write transaction, perform the following steps:

1. Set the selected PMA control ports to the desired settings (for example, `tx_vodctrl = 3'b001`).
2. Set the `logical_channel_address` input port to the logical channel address of the transceiver channel whose PMA controls you want to reconfigure.
3. Set the `rx_tx_duplex_sel` port to `2'b10` so that only the transmit PMA controls are written to the transceiver channel.
4. Ensure that the busy signal is low before you start a write transaction.
5. Assert the `write_all` signal for one `reconfig_clk` clock cycle.

The busy output status signal is asserted high to indicate that the dynamic reconfiguration controller is busy writing the PMA control values. When the write transaction has completed, the busy signal goes low.



## DC Characteristics

This section lists the I/O leakage current, pin capacitance, on-chip termination (OCT) tolerance, and bus hold specifications for Cyclone IV devices.

### Supply Current

The device supply current requirement is the minimum current drawn from the power supply pins that can be used as a reference for power size planning. Use the Excel-based early power estimator (EPE) to get the supply current estimates for your design because these currents vary greatly with the resources used. Table 1-6 lists the I/O pin leakage current for Cyclone IV devices.

**Table 1-6. I/O Pin Leakage Current for Cyclone IV Devices <sup>(1), (2)</sup>**

Symbol	Parameter	Conditions	Device	Min	Typ	Max	Unit
$I_I$	Input pin leakage current	$V_I = 0\text{ V to }V_{CCIOMAX}$	—	-10	—	10	$\mu\text{A}$
$I_{OZ}$	Tristated I/O pin leakage current	$V_O = 0\text{ V to }V_{CCIOMAX}$	—	-10	—	10	$\mu\text{A}$

**Notes to Table 1-6:**

- (1) This value is specified for normal device operation. The value varies during device power-up. This applies for all  $V_{CCIO}$  settings (3.3, 3.0, 2.5, 1.8, 1.5, and 1.2 V).
- (2) The 10  $\mu\text{A}$  I/O leakage current limit is applicable when the internal clamping diode is off. A higher current can be observed when the diode is on.

### Bus Hold

The bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1-7 lists bus hold specifications for Cyclone IV devices.

**Table 1-7. Bus Hold Parameter for Cyclone IV Devices (Part 1 of 2) <sup>(1)</sup>**

Parameter	Condition	V <sub>CCIO</sub> (V)												Unit
		1.2		1.5		1.8		2.5		3.0		3.3		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus hold low, sustaining current	V <sub>IN</sub> > V <sub>IL</sub> (maximum)	8	—	12	—	30	—	50	—	70	—	70	—	μA
Bus hold high, sustaining current	V <sub>IN</sub> < V <sub>IL</sub> (minimum)	−8	—	−12	—	−30	—	−50	—	−70	—	−70	—	μA
Bus hold low, overdrive current	0 V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	125	—	175	—	200	—	300	—	500	—	500	μA
Bus hold high, overdrive current	0 V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	−125	—	−175	—	−200	—	−300	—	−500	—	−500	μA

**Table 1-25. PLL Specifications for Cyclone IV Devices <sup>(1), (2)</sup> (Part 2 of 2)**

Symbol	Parameter	Min	Typ	Max	Unit
$t_{DLOCK}$	Time required to lock dynamically (after switchover, reconfiguring any non-post-scale counters/delays or $\overline{areset}$ is deasserted)	—	—	1	ms
$t_{OUTJITTER\_PERIOD\_DEDCLK}$ <sup>(6)</sup>	Dedicated clock output period jitter $F_{OUT} \geq 100$ MHz	—	—	300	ps
	$F_{OUT} < 100$ MHz	—	—	30	mUI
$t_{OUTJITTER\_CCJ\_DEDCLK}$ <sup>(6)</sup>	Dedicated clock output cycle-to-cycle jitter $F_{OUT} \geq 100$ MHz	—	—	300	ps
	$F_{OUT} < 100$ MHz	—	—	30	mUI
$t_{OUTJITTER\_PERIOD\_IO}$ <sup>(6)</sup>	Regular I/O period jitter $F_{OUT} \geq 100$ MHz	—	—	650	ps
	$F_{OUT} < 100$ MHz	—	—	75	mUI
$t_{OUTJITTER\_CCJ\_IO}$ <sup>(6)</sup>	Regular I/O cycle-to-cycle jitter $F_{OUT} \geq 100$ MHz	—	—	650	ps
	$F_{OUT} < 100$ MHz	—	—	75	mUI
$t_{PLL\_PSERR}$	Accuracy of PLL phase shift	—	—	$\pm 50$	ps
$t_{ARESET}$	Minimum pulse width on $\overline{areset}$ signal.	10	—	—	ns
$t_{CONFIGPLL}$	Time required to reconfigure scan chains for PLLs	—	3.5 <sup>(7)</sup>	—	SCANCLK cycles
$f_{SCANCLK}$	$scanclk$ frequency	—	—	100	MHz
$t_{CASC\_OUTJITTER\_PERIOD\_DEDCLK}$ <sup>(8), (9)</sup>	Period jitter for dedicated clock output in cascaded PLLs ( $F_{OUT} \geq 100$ MHz)	—	—	425	ps
	Period jitter for dedicated clock output in cascaded PLLs ( $F_{OUT} < 100$ MHz)	—	—	42.5	mUI

**Notes to Table 1-25:**

- (1) This table is applicable for general purpose PLLs and multipurpose PLLs.
- (2) You must connect  $V_{CCD\_PLL}$  to  $V_{CCINT}$  through the decoupling capacitor and ferrite bead.
- (3) This parameter is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.
- (4) The  $V_{CO}$  frequency reported by the Quartus II software in the PLL Summary section of the compilation report takes into consideration the  $V_{CO}$  post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the  $f_{VCO}$  specification.
- (5) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source that is less than 200 ps.
- (6) Peak-to-peak jitter with a probability level of  $10^{-12}$  (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL when an input jitter of 30 ps is applied.
- (7) With 100-MHz  $scanclk$  frequency.
- (8) The cascaded PLLs specification is applicable only with the following conditions:
  - Upstream PLL— $0.59 \text{ MHz} \leq \text{Upstream PLL bandwidth} < 1 \text{ MHz}$
  - Downstream PLL—Downstream PLL bandwidth  $> 2 \text{ MHz}$
- (9) PLL cascading is not supported for transceiver applications.